

# Low Temperature Solders for 1st Level Interconnection Packaging

## Motivation:

- Selection of materials for packaging interconnect is critical.
- The temperature profile required to effect a particular stage should not compromise the integrity or reliability of previous stages.
- The function provided in each stage should not be susceptible to damage by the thermal profiles required by subsequent stages in the manufacture of the package, including testing, and final assembly of the device into the end products.

## Objective:

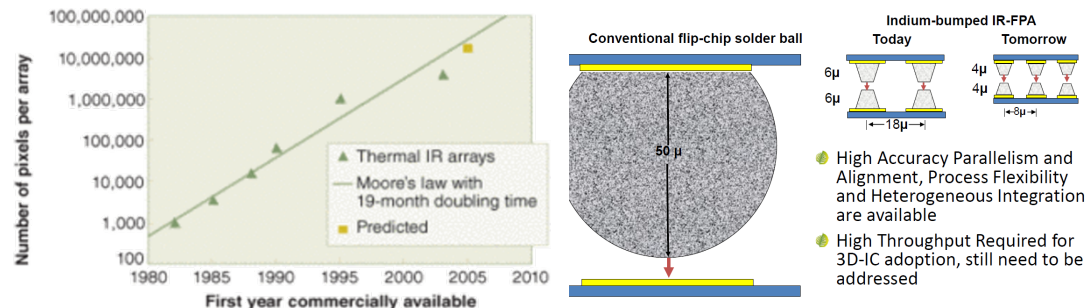
- Provide data-based guidance on the characterization and selection of interconnect materials that can deliver an overall reduction on the process temperature required in the first level construction of IC packages.

## Strategy/Approach:

- Research low temp solder materials, soldering technology and applicable products.
- Develop and publish characterization and selection guidelines.

## Longer Term:

- Recommendations to standard body.



## Status:

- Concept development led by Indium and IBM
- Packaging TIG workgroup defining concept
- Open to new participants
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